2SJ450

Silicon P-Channel MOS FET

HITACHI

ADE-208-381 1st. Edition

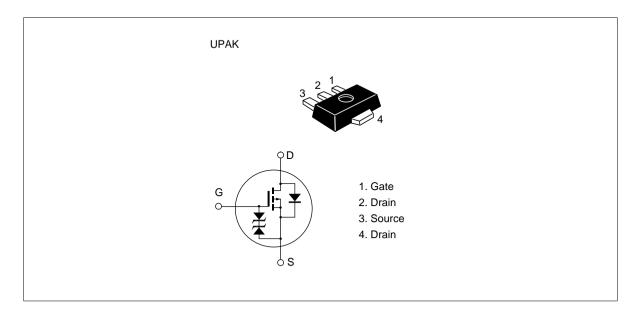
Application

High speed power switching

Features

- Low on-resistance.
- Low drive power
- High speed switching
- 2.5 V gate drive device.

Outline



2SJ450

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	-60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	-1	A
Drain peak current	l _{D(pulse)} *1	-2	A
Drain peak current	I _{DR}	-1	A
Channel dissipation	Pch*2	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

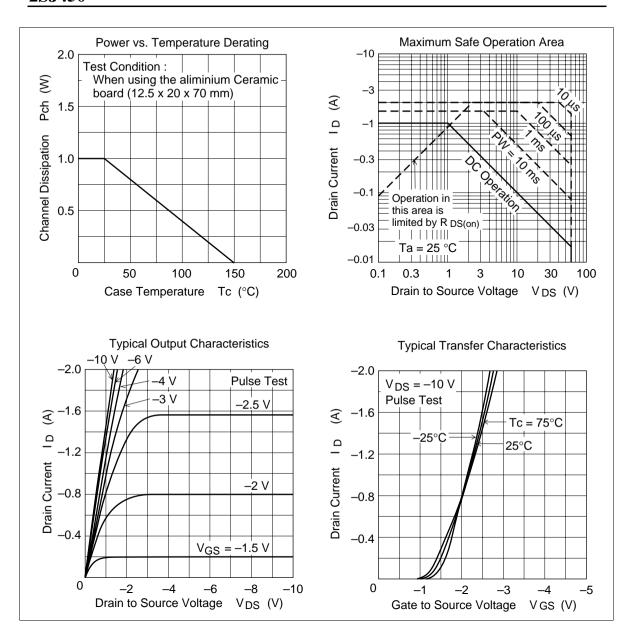
Notes: 1. PW \leq 100 μ s, duty cycle \leq 10%

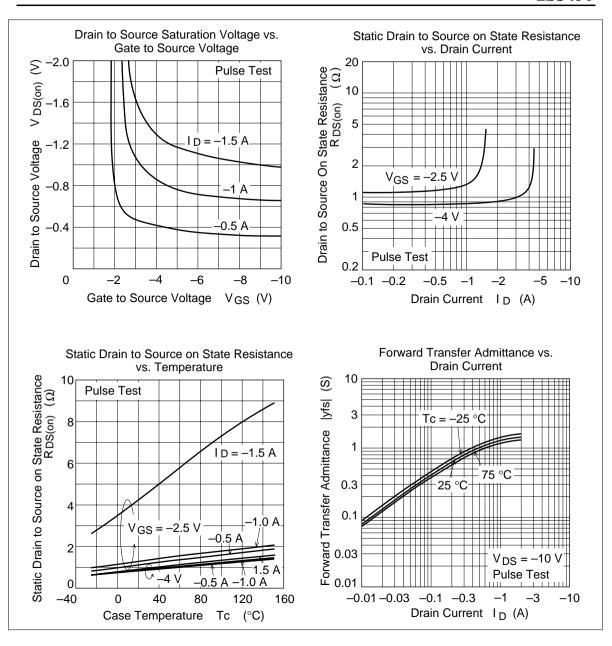
^{2.} When using aluminium ceramic board (12.5 \times 20 \times 70 mm)

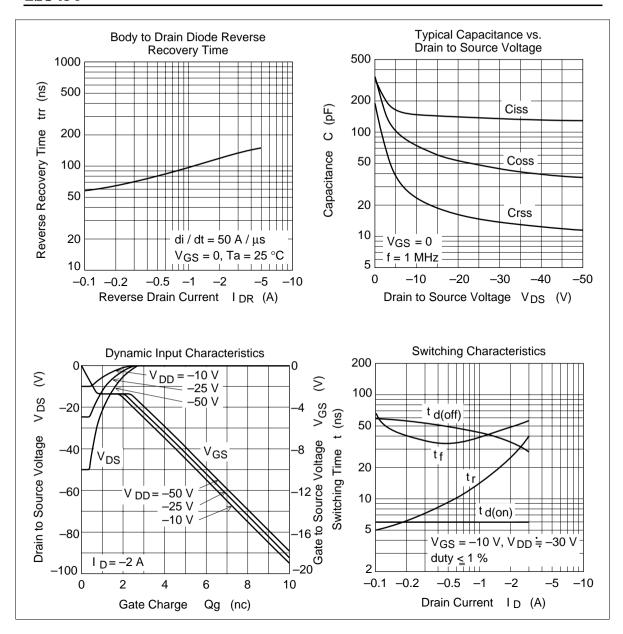
Electrical Characteristics ($Ta = 25^{\circ}C$)

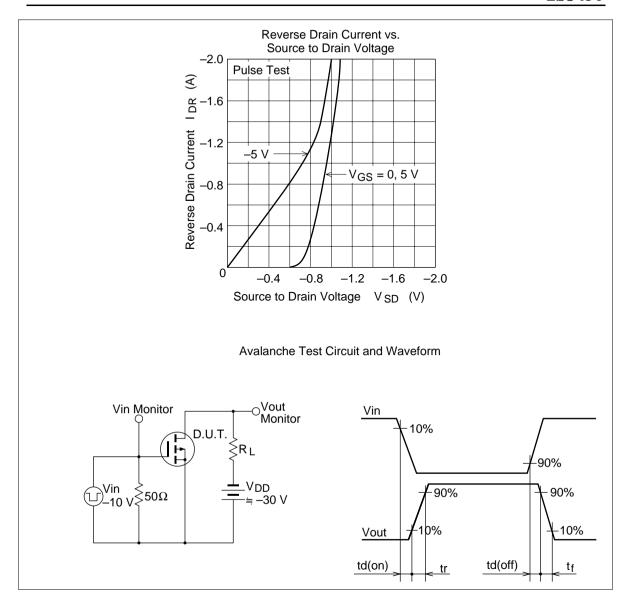
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-60	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	- 50	μΑ	$V_{DS} = -50 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{\rm GS(off)}$	-0.5	_	-1.5	V	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$
Static drain to source on state resistance	R _{DS(on)}	_	0.85	1.2	Ω	$I_D = -0.5 \text{ A}$ $V_{GS} = -4 \text{ V}^{*1}$
Static drain to source on state resistance	R _{DS(on)}	_	1.1	1.9	Ω	$I_D = -0.3 \text{ A}$ $V_{GS} = -2.5 \text{ V}^{*1}$
Fowerd transfer admittance	$ y_{fs} $	0.6	1.0	_	S	$I_D = -0.5 \text{ A}$ $V_{DS} = -10 \text{ V}$
Input capacitance	Ciss	_	150	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	72	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	24	_	pF	f = 1 MHz
Turn-on delay time	$t_{\text{d(on)}}$	_	6	_	ns	$V_{GS} = -10 \text{ V}, I_{D} = -0.5 \text{ A}$
Rise time	t _r	_	9	_	ns	$R_L = 60 \Omega$
Turn-off delay time	t _{d(off)}	_	50	_	ns	
Fall time	t _f	_	35	_	ns	
Body to drain diode forward voltage	V_{DF}		-0.9		V	$I_F = -1 A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	100	_	ns	$I_F = -1 \text{ A}, V_{GS} = 0$ diF/dt = 50A/ μ s

Note: 1. Pulse Test Marking is "UY".

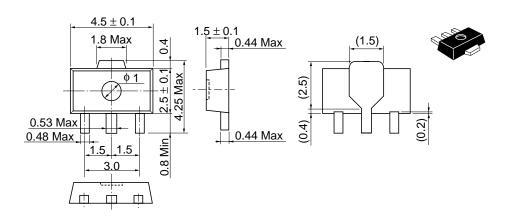








Unit: mm



Hitachi Code	UPAK
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.050 g

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